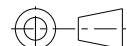


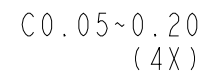
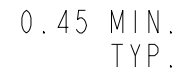


spec ref -		dr		Jeny Ren	2018/05/09	projection 	mm 	size	A3	scale	2:1
tolerance std ISO 406 ISO 1101	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng		Girder Liang	2018/11/20			ecn no	ELX-DG-31888-1		
		chr		-	-			rel level Released			
		appr		Nickor Zuo	2018/11/21	product family -					
surface -  ISO 1302	linear	0.X	±0.30	Amphenol FCI	title	DDR4 288 PIN DIMM CONNECTOR		dwg no	10147563		rev B
		0.XX	±0.20								
		0.XXX	±0.10								
		angular	0°	±2°		cat. no.	-	Product - Customer Drw		sheet 1 of 4	

D

RECOMMENDED PCB LAYOUT
MORE INFORMATION REFER TO JEDEC SO-017

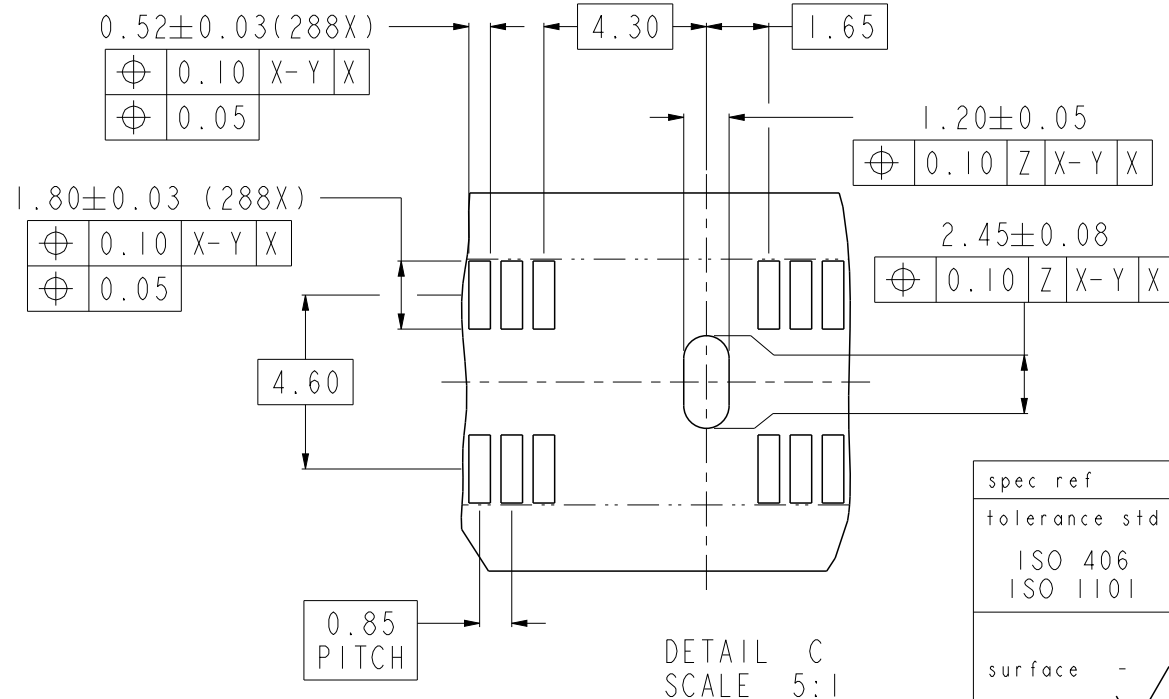
6.50 MAX.
KEEP OUT ZONE

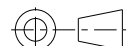
SEE DETAIL C

THICKNESS
1.6~3.2mm

ADDITIONAL NOTES:

1. RECOMMENDED STENCIL THICKNESS IS NOT LESS THAN 0.15mm



spec ref -				dr		Jeny Ren	2018/05/09		projection		mm	size		A3	scale		2:1		
tolerance std				eng		Girder Liang	2018/11/20					ecn no		ELX-DG-31888-1					
ISO 406				chr		-	-					rel level		Released					
ISO 1101				appr		Nickor Zuo	2018/11/21					product family		-					
surface -		linear	0.X		±0.30		Amphenol FCI	title	DDR4 288 PIN DIMM CONNECTOR						dwg no	10147563		rev	B
			0.XX		±0.20				SMT TERMINATION										
			0.XXX		±0.10														
ISO 1302		angular	0°		±2°		cat. no.		-		Product - Customer Drw						sheet 3 of 4		

PRODUCT PART NUMBER

10147563-

ADDITIONAL REQUIREMENTS

I: LOW HALOGEN COMPLIANT

HOLD DOWNS CONFIGURATIONS

0: 3 FORKLOCKS,LENGTH "L"=4.00±0.25
1: 3 FORKLOCKS,LENGTH "L"=2.50±0.25
3: 3 SOLDER TABS,LENGTH"L"=2.00±0.25
5: 2 SOLDER TABS AT BOTH END (LENGTH "L"=2.00±0.25)
+1 FORKLOCK AT MIDDLE (LENGTH "L"=2.50±0.25)
6: 3 SOLDER TABS,LENGTH"L"=1.50±0.25

MYLAR, CAP AND PACKAGE

0. WITH 30MM LENGTH MYLAR,HARD TRAY PACKAGE
1. WITHOUT MYLAR AND CAP, HARD TRAY PACKAGE
2. WITH CAP, HARD TRAY PACKAGE
3. WITH 90MM LENGTH MYLAR,HARD TRAY PACKAGE

HOUSING COLOR

0: NATURAL
1: BLACK
2: BLUE

EJECTOR TYPE

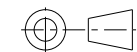


J: NATURAL
K: BLACK
B: BLUE

CONTACT AREA PLATING

CODE	CONTACT AREA	SOLDER TAIL AREA
11LF	15u" MIN.GOLD	100u" MIN.
13LF	30u" MIN.GOLD	100% MATTE TIN

NOTES:

1. MATERIALS:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILBER FILLED, UL94 V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILBER FILLED, UL94 V-0 RATED.
TERMINAL: COPPER ALLOY
FORKLOCK: COPPER ALLOY
SOLDER TAB:COPPER ALLOY
2. STENCIL THICKNESS IS NOT LESS THAN 0.15mm.
3. DATE CODE"MMDDYYL",MMDDYY IS ASSEMBLY DATE,
L IS FCI PRODUCTION LINE.
4. SPECIFICATION:
PRODUCTION SPECIFICATION: FCI GS-12-1092.
PACKAGE SPECIFICATION: FCI GS-14-2267.
APPLICATION SPECIFICATION: FCI GS-20-0353.
5. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS
AS DESCRIBED IN FCI GS-22-008.
6. THIS PRODUCT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS
IN REFLOW SOLDERING APPLICATION.

spec ref -				dr		Jeny Ren	2018/05/09		projection		mm		size		A3	scale		1:1						
tolerance ref std		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng		Girder Liang	2018/11/20						ecn no				ELX-DG-31888-1					
ISO 406						chr		-	-						rel level				Released					
ISO 1101						appr		Nickor Zuo		2018/11/21		product family						-						
surface -  ISO 1302		linear		0.X		±0.30		Amphenol FCi		title		DDR4 288 PIN DIMM CONNECTOR		dwg no		10147563		rev		B				
																					0.XX		±0.20	
																					0.XXX		±0.10	
		angular		0°		±2°															cat. no.		-	Product - Customer Drw